

ABSTRACT OF THE DISCLOSURE

A semiconductor device includes a lead electrode connected to a lead, a case electrode having a projection part around its periphery, and a semiconductor chip having a rectification function and connected electrically between the lead electrode and the case electrode through connection members, wherein an electrically conductive plate is provided between the semiconductor chip and the lead electrode. Thereby, any of cracks is prevented from being generated in the semiconductor chip due to the mutual thermal deformation difference between the electrically conductive plate and the semiconductor chip which are electrically joined to each other through a joining member.